

ABSTRACT

Processes are described to remove substances from substrates, for example, electronic devices. In an embodiment, a process may include

5 providing a substrate including a first side and a second side with a substance being disposed on at least a portion of the first side of the substrate. The process may also include contacting the substrate with a solution such that the first side of the substrate is coated with the solution, at least a portion of the second side is free of the solution and at least a portion of the substance

10 is released from the first side of the substrate. Additionally, the process may include rinsing the substrate to remove at least a portion of the substance released from the first side of the substrate. The process may be suitable for removing and, in some instances, completely dissolving photoresists of the positive and negative varieties.